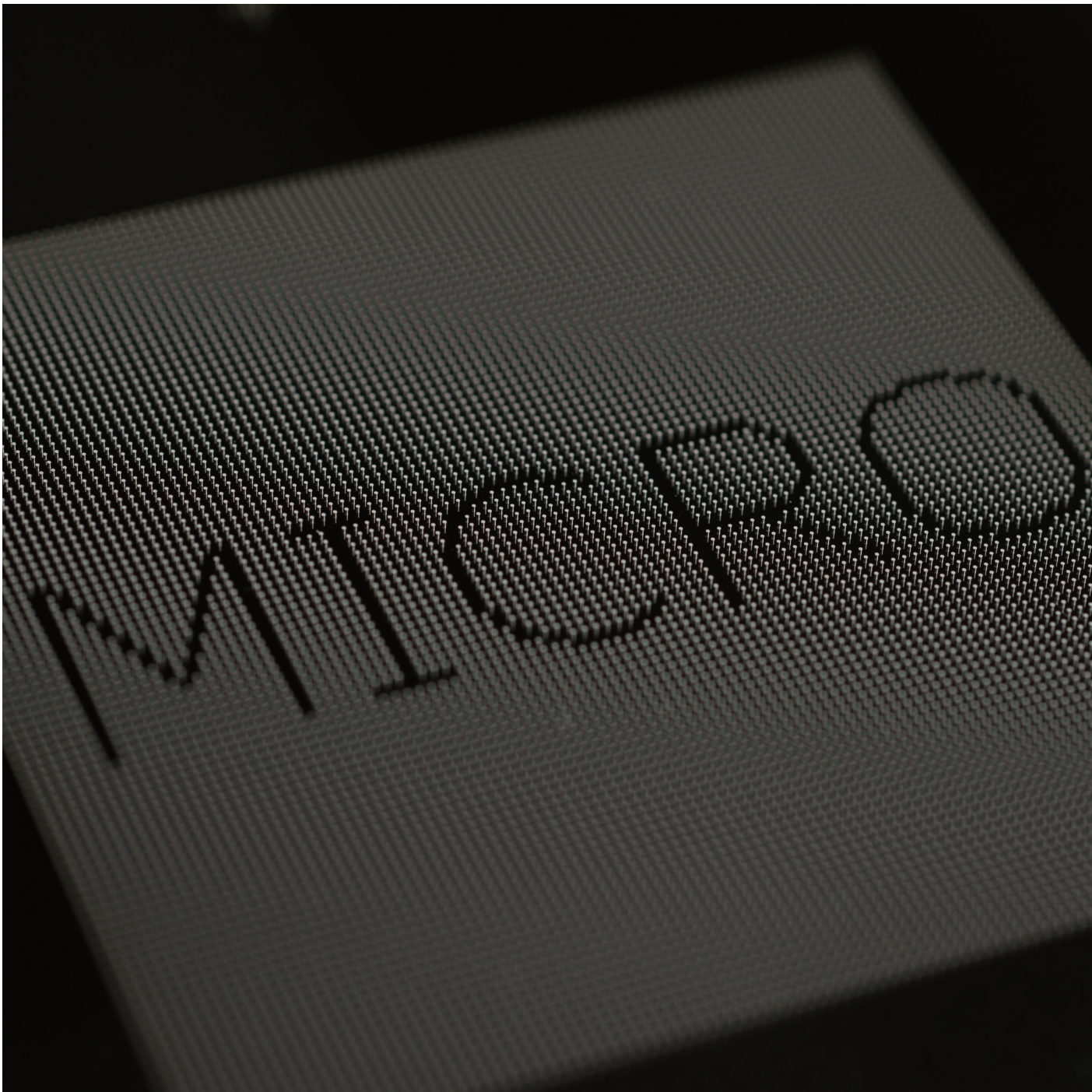


技術資料

TECNICAL INFOMATION



TGV (ガラス貫通穴あけ基板)

TGV (Through Glass Via)

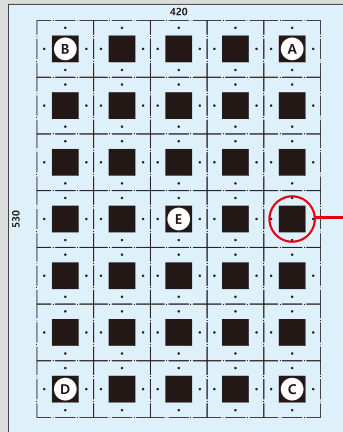
大判ガラスに均一性のある高精度の穴あけを施します。

We can make through-hole vias in large-size glass with high precision and uniformity.

■ Specifications

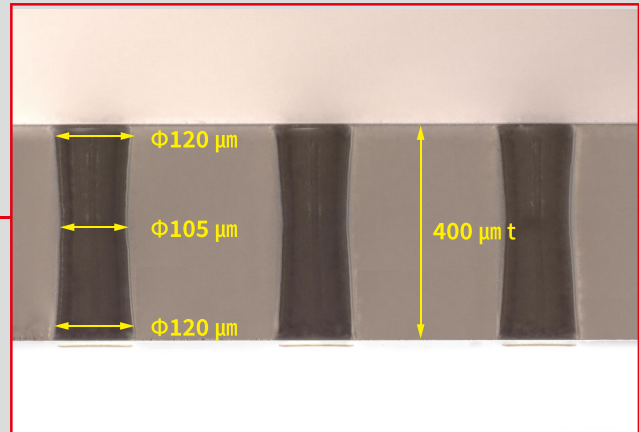
Substrate size	420 mm × 530 mm (0.4 mm t)
Number of holes	350,000 holes (10,000 holes × 35 faces)
Hole diameter	Φ120 μm (hourglass shape)

■ Measurement point

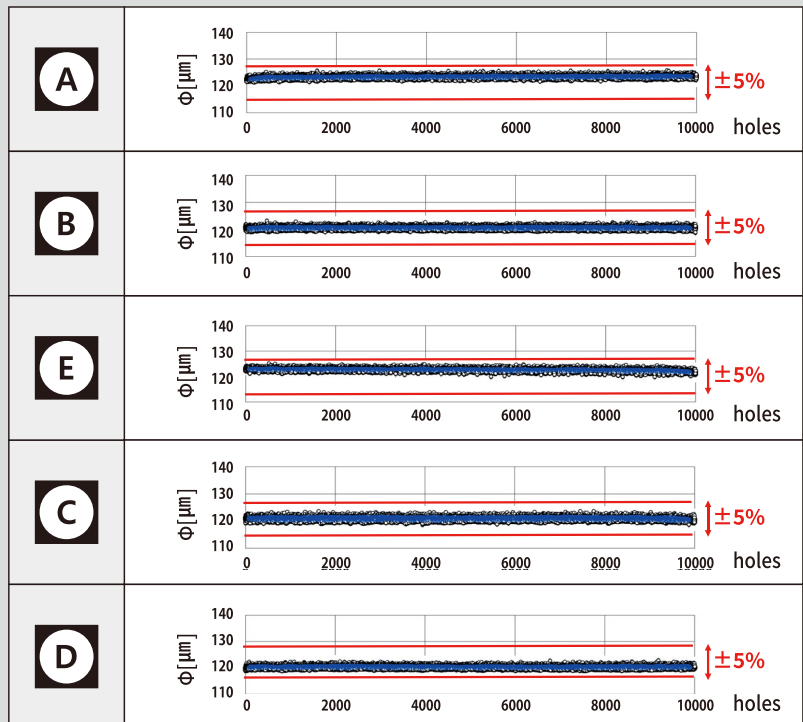


Overview: 10,000 holes × 35 faces

■ TGV [cross section]



■ TGV diameter measurement data



ガラス穴あけ両面配線基板

Double-sided wiring TGV substrate

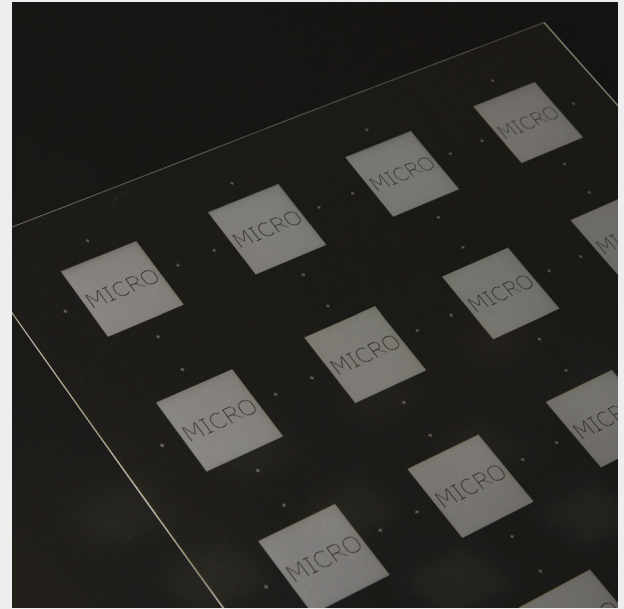
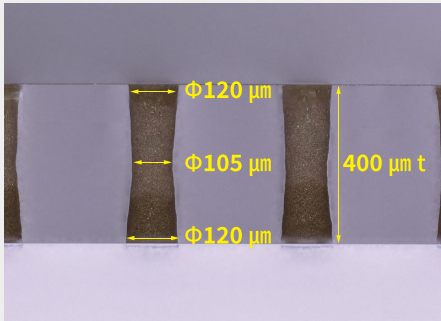
TGVへの穴埋めと両面配線加工を施します。

We can apply double-sided wiring on a TGV substrate by filling through-hole vias in it.

■ Specifications

Hole filling	Copper paste (fill type)
Wiring	• Seed layer: Ti • Semi-additive copper plating, thickness: 10 μm • Minimum line width: L/S = 10 μm / 10 μm

■ TGV filling with copper paste [cross section]



薄板ガラス (0.2 mm t) への穴あけ両面配線部品 (10 mm sq.)

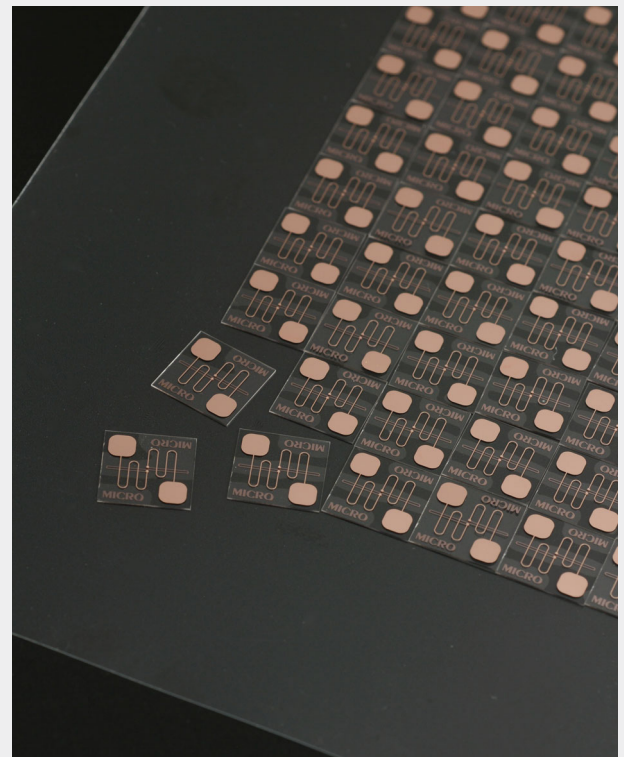
Thin-glass part (0.2 mm t) with through-hole vias for double-sided wiring (10 mm sq.)

0.2t の薄板ガラスに穴あけ加工と穴埋め加工を施し両面電極配線を可能にしたガラスです。

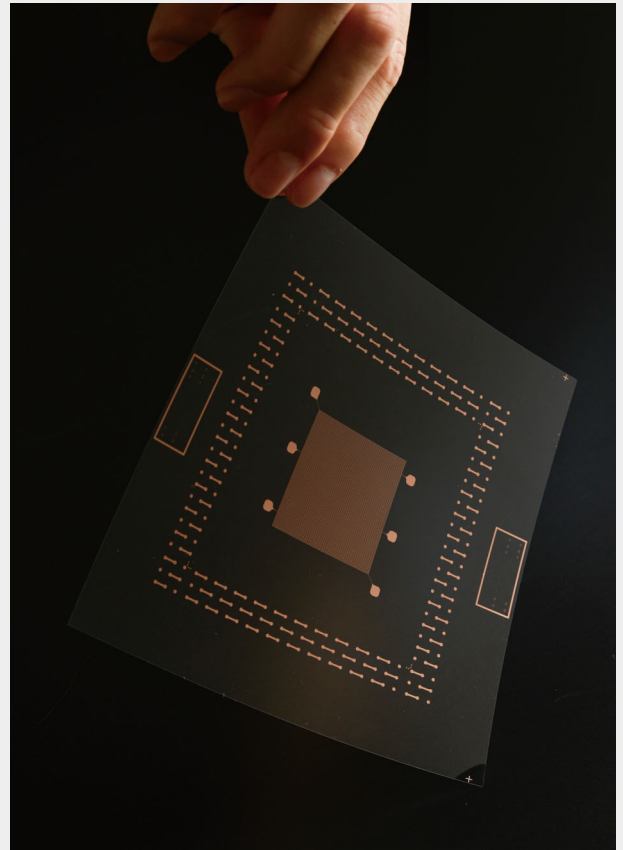
This is a thin-glass part fabricated by making through-hole vias in thin glass with a thickness of 0.2t and filling the through-hole vias, which enables double-sided electrode wiring.

■ Specifications

Substrate size	6 in. (150 mm sq.)
Plate thickness	0.2 $\mu\text{m t}$
Hole processing	$\Phi 100 \mu\text{m}$
Wiring	• Seed layer: Ti • Semi-additive copper plating, thickness: 10 μm
Hole filling	• Copper paste (fill type) • Conformal



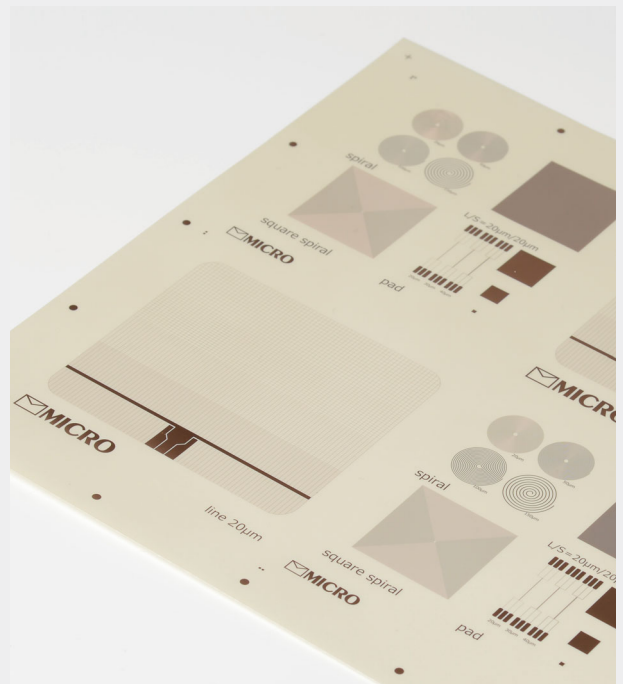
超薄板ガラス配線基板 Ultra-thin glass wiring substrate



■ Specifications

Thickness 20 μm , 30 μm , 50 μm

LCP 樹脂フィルム配線基板 (液晶ポリマー) LCP (liquid crystal polymer) resin film wiring substrate



■ Specifications

Adhesion	1 kN or more
Maximum processing dimension	400 mm × 500 mm
Film thickness	0.05 mm t
Conductor thickness	Semi-additive copper plating, 5 μm t
Line width	L/S = 20 / 20 μm

株式会社 ミクロ技術研究所
MICRO TECHNOLOGY CO., LTD.

〒151-0063 東京都渋谷区富ヶ谷 1-33-14
TEL:03-3469-1133 / FAX:03-3469-1557

INQUIRY

TEL: 03-3469-1133

E-mail: sales@microtc.com

HP : www.microtc.com

